

M80C196KB

16-Bit High Performance CHMOS Microcontroller

The M80C196KB 16-bit microcontroller is a high performance member of the MCS-96 microcontroller family. The M80C196KB is pin-for-pin compatible and uses a true superset of the M8096 instructions. Intel's CHMOS process provides a high performance processor along with low power consumption. To further reduce power requirements, the processor can be placed into Idle or Powerdown Mode.

Four high-speed capture inputs are provided to record times when events occur. Six high-speed outputs are available for pulse or waveform generation. The high-speed output can also generate four software timers or start an A/D conversion. Events can be based on the timer or up/down counter.

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- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
 - · Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

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M80C196KB 16-BIT HIGH PERFORMANCE CHMOS MICROCONTROLLER

Military

- **■** 232 Byte Register File
- Register-to-Register Architecture
- 28 Interrupt Sources/16 Vectors
- # 2.3 μs 16 x 16 Multiply (12 MHz)
- 4.0 µs 32/16 Divide (12 MHz)
- Powerdown and Idle Modes
- Five 8-Bit I/O Ports
- 16-Bit Watchdog Timer
- Dynamically Configurable 8-Bit or 16-Bit Buswidth
- Available in 68-Lead PGA and 68-Lead Ceramic Quad Flat Pack

- Full Duplex Serial Port
- High Speed I/O Subsystem
- **16-Bit Timer**
- 16-Bit Up/Down Counter with Capture
- Pulse-Width-Modulated Output
- Four 16-Bit Software Timers
- 10-Bit A/D Converter with S/H
- 12 MHz Version M80C196KB
- Available in Two Product Grades:

 MIL-STD-883, -55°C to +125°C (T_C)

 Military Temperature Only (MTO),

 -55°C to +125°C (T_C)

The M80C196KB 16-bit microcontroller is a high performance member of the MCS®-96 microcontroller family. The M80C196KB is pin-for-pin compatible and uses a true superset of the M8096 instructions. Intel's CHMOS process provides a high performance processor along with low power consumption. To further reduce power requirements, the processor can be placed into Idle or Powerdown Mode.

Bit, byte, word and some 32-bit operations are available on the M80C196KB. With a 12 MHz oscillator a 16-bit addition takes 0.66 μ s, and the instruction times average 0.5 μ s to 1.5 μ s in typical applications.

Four high-speed capture inputs are provided to record times when events occur. Six high-speed outputs are available for pulse or waveform generation. The high-speed output can also generate four software timers or start an A/D conversion. Events can be based on the timer or up/down counter.

Also provided on-chip are an A/D converter with Sample and Hold, serial port, watchdog timer, and a pulse-width-modulated output signal.

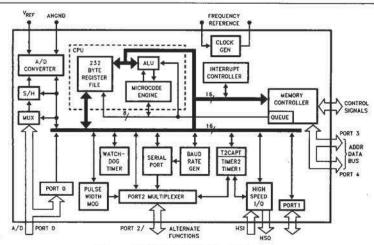


Figure 1. M80C196KB Block Diagram

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ARCHITECTURE

The M80C196KB is a member of the MCS®-96 family, and as such has the same architecture and uses the same instruction set as the M8096. Many new features have been added on the M80C196KB including:

CPU FEATURES

Divide by 2 instead of divide by 3 clock for 1.5X performance

Faster instructions, especially indexed/indirect data operations

2.33 μ s 16 imes 16 multiply with 12 MHz clock (was 6.25 μ s) on the 8096

Faster interrupt response (almost twice as fast as 8096)

Powerdown and Idle Modes

6 new instructions including Compare Long and Block Move

8 new interrupt vectors/6 new interrupt sources

PERIPHERAL FEATURES

SFR Window switching allows read-only registers to be written and vice-versa

Timer2 can count up or down by external selection

Timer2 has an independent capture register

HSO line events are stored in a register

HSO has CAM Lock and CAM Clear commands

New Baud Rate values are needed for serial port, higher speeds possible in all modes

Double buffered serial port transmit register

Serial Port Receive Overrun and Framing Error Detection

PWM has a Divide-by-2 Prescaler



NEW INSTRUCTIONS

```
PUSHA - PUSHes the PSW, IMASK, IMASK1, and WSR
           (Used instead of PUSHF when new interrupts and registers are used.)
           assembly language format: PUSHA
           object code format: <11110100>
           bytes: 1
           states: on-chip stack: 12
                  off-chip stack: 18
           POPs the PSW, IMASK, IMASK1, and WSR
POPA
           (Used instead of POPF when new interrupts and registers are used.)
           assembly language format: POPA
           object code format: <11110101>
           bytes: 1
           states: on-chip stack: 12
                  off-chip stack:18
IDLPD - Sets the part into Idle or Powerdown Mode
           assembly language format: IDLPD #key (key=1 for Idle, key=2 for Powerdown.)
           object code format: <11110110> <key>
           bytes: 2
           states: legal key: 8
                 illegal key: 25
DJNZW - Decrement Jump Not Zero using a Word counter
           assembly language format: DJNZW wreg, cadd
           object code format: <11100001> <wreg> <disp>
           bytes: 3
           states: jump not taken: 6
                 jump taken: 10
CMPL
          - Compare 2 long direct values
                                                DST SRC
           assembly language format:
                                     CMPL
                                               Lreg, Lreg
           object code format: <11000101> <src Lreg> <dst Lreg>
           bytes: 3
           states: 7
BMOV — Block move using 2 auto-incrementing pointers and a counter
                                                PTRS CNTREG
           assembly language format:
                                     BMOV
                                                Lreg, wreg
           object code format: <11000001> <wreg> <Lreg>
           bytes: 3
                     internal/internal: 8 per transfer + 6
           states:
                     external/internal: 11 per transfer + 6
                     external/external: 14 per transfer + 6
```



SFR OPERATION

All of the registers that were present on the M8096 work the same way as they did, except that the baud rate value is different. The new registers shown in the memory map control new functions. The most important new register is the Window Select Register (WSR) which allows reading of the formerly write-only registers and vice-versa. Using the WSR is described later in this data sheet.

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PACKAGING

The M80C196KB is available in a ceramic pin grid array, shown in Figure 2, and a leaded ceramic quad pack shown in Figure 3. A comparison of the pinouts for both of these package types is shown in Tables 1a-1c.

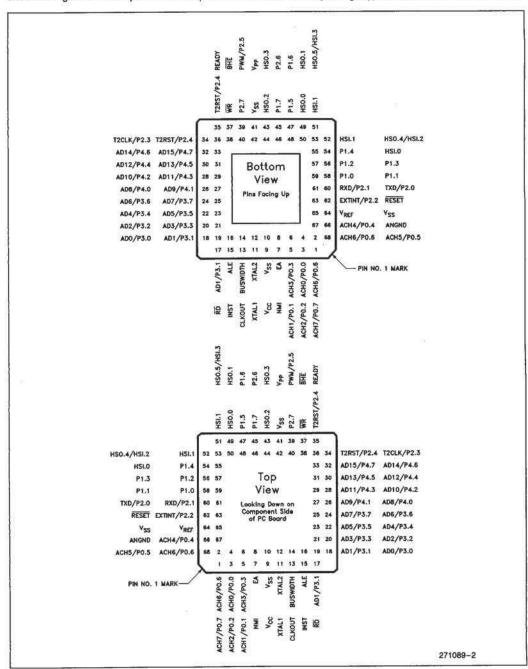


Figure 2. Pin Grid Array Pinout



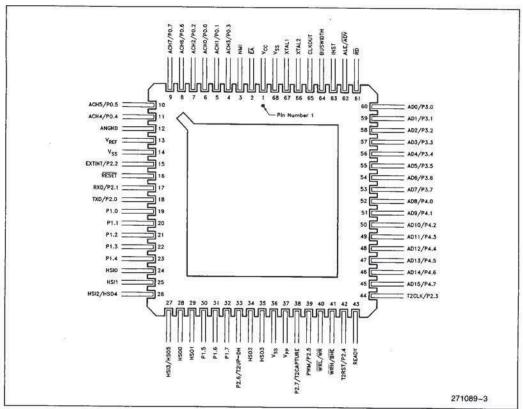


Figure 3. 68-Lead Ceramic Quad Flat Pack Pinout

Table 1a. M80C196KB Pinout - in PGA Pin Order

PGA	Signal	
1	ACH7/P0.7	
2	ACH6/P0.6	
3	ACH2/P0.2	
4	ACH0/P0.0	
5	ACH1/P0.1	
6	ACH3/P0.3	
7	NMI	
8	EA	
9	Vcc	
10	VSS	
11	XTAL1	
12	XTAL2	
13	CLKOUT	
14	BUSWIDTH	
15	INST	
16	ALE/ADV	
17	RD	
18	AD0/P3.0	
19	AD1/P3.1	
20	AD2/P3.2	
21	AD3/P3.3	
22	AD4/P3.4	
23	AD5/P3.5	

PGA	Signal
24	AD6/P3.6
25	AD7/P3.7
26	AD8/P4.0
27	AD9/P4.1
28	AD10/P4.2
29	AD11/P4.3
30	AD12/P4.4
31	AD13/P4.5
32	AD14/P4.6
33	AD15/P4.7
34	T2CLK/P2.3
35	READY
36	T2RST/P2.4/AINC
37	BHE/WRH
38	WR/WRL
39	PWM/P2.5
40	T2CAPTURE/P2.7/PACT
41	V _{PP}
42	V _{SS}
43	HS0.3
44	HS0.2
45	T2UP-DN/P2.6
46	P1.7

PGA	Signal
47	P1.6
48	P1.5
49	HSO.1
50	HSO.0
51	HSO.5/HSI.3
52	HSO.4/HSI.2
53	HSI.1
54	HSI.0
55	P1.4
56	P1.3
57	P1.2
58	P1.1
59	P1.0
60	TXD/P2.0
61	RXD/P2.1
62	RESET
63	EXTINT/P2.2
64	V _{SS}
65	VREF
66	ANGND
67	ACH4/P0.4
68	ACH5/P0.5

PRELIMINARY



Table 1b. M80C196KB Pinout — in CQFP Pin Order

CQFP	Signal	
1	V _{CC}	
2	EA	
3	NMI	
4	ACH3/P0.3	
5	ACH1/P0.1	
6	ACH0/P0.0	
7	ACH2/P0.2	
8	ACH6/P0.6	
9	ACH7/P0.7	
10	ACH5/P0.5	
11	ACH4/P0.4	
12	ANGND	
13	VREF	
14	VSS	
15	EXTINT/P2.2	
16	RESET	
17	RXD/P2.1	
18	TXD/P2.0	
19	P1.0	
20	P1.1	
21	P1.2	
22	P1.3	
23	P1.4	

CQFP	Signal
24	HSI.0
25	HSI.1
26	HSO.4/HSI.2
27	HSO.5/HSI.3
28	HSO.0
29	HSO.1
30	P1.5
31	P1.6
32	P1.7
33	T2UP-DN/P2.6
34	HSO.2
35	HSO.3
36	V _{SS}
37	V _{PP}
38	T2CAPTURE/P2.7/PACT
39	PWM/P2.5
40	WR/WRL
41	BHE/WRH
42	T2RST/P2.4/AINC
43	READY
44	T2CLK/P2.3
45	AD15/P4.7
46	AD14/P4.6

CQFP	Signal
47	AD13/P4.5
48	AD12/P4.4
49	AD11/P4.3
50	AD10/P4.2
51	AD9/P4.1
52	AD8/P4.0
53	AD7/P3.7
54	AD6/P3.6
55	AD5/P3.5
56	AD4/P3.4
57	AD3/P3.3
58	AD2/P3.2
59	AD1/P3.1
60	AD0/P3.0
61	RD
62	ALE/ADV
63	INST
64	BUSWIDTH
65	CLKOUT
66	XTAL2
67	XTAL1
68	VSS

Table 1c. M80C196KB Pinout — in Signal Order

Signal	PGA	CQFP		
ACH0/P0.0	4	6		
ACH1/P0.1	5	5		
ACH2/P0.2	3	7		
ACH3/P0.3	6	4		
ACH4/P0.4	67	11		
ACH5/P0.5	68	10		
ACH6/P0.6	2	8		
ACH7/P0.7	1	9		
P1.0	59	19		
P1.1	58	20		
P1.2	57	21		
P1.3	56	22		
P1.4	55	23		
P1.5	48	30		
P1.6	47	31		
P1.7	46	32		
TXD/P2.0	60	18		
RXD/P2.1	61	17		
EXTINT/P2.2	63	15		
T2CLK/P2.3	34	. 44		
T2RST/P2.4/AINC	36	42		
PWM/P2.5	39	39		
T2UP-DN/P2.6	45	33		

Signal	PGA	COFP
T2CAPTURE/P2.7/PACT	40	38
AD0/P3.0	18	60
AD1/P3.1	19	59
AD2/P3.2	20	58
AD3/P3.3	21	57
AD4/P3.4	22	56
AD5/P3.5	23	55
AD6/P3.6	24	54
AD7/P3.7	25	53
AD8/P4.0	26	52
AD9/P4.1	27	51
AD10/P4.2	28	50
AD11/P4.3	29	49
AD12/P4.4	30	48
AD13/P4.5	31	47
AD14/P4.6	32	46
AD15/P4.7	33	45
HSO.0	50	28
HSO.1	49	29
HSO.2	44	34
HSO.3	43	35
HSO.4/HSI.2	52	26
HSO.5/HSI.3	51	27

Signal	PGA	CQFP
HSI.0	54	24
HSI.1	53	25
RD	17	61
WR/WRL	38	40
BHE/WRH	37	41
BUSWIDTH	14	64
ALE/ADV	16	62
EA	. 8	2
INST	15	63
READY	35	43
NMI	7	3
RESET	62	16
XTAL1	11	67
XTAL2	12	66
CLKOUT	13	65
ANGND	66	12
VREF	65	13
Vpp	41	37
Vcc	9	1
VSS	10	68
VSS	42	36
VSS	64	14



PIN DESCRIPTIONS

Symbol	Name and Function
V _{CC}	Main supply voltage (5V).
V _{SS}	Digital circuit ground (0V). There are three V _{SS} pins, all of which must be connected.
V _{REF}	Reference voltage for the A/D converter (5V). V _{REF} is also the supply voltage to the analog portion of the A/D converter and the logic used to read Port 0. Must be connected for A/D and Port 0 to function.
ANGND	Reference ground for the A/D converter. Must be held at nominally the same potential as Vss.
V _{PP}	Timing pin for the return from powerdown circuit. Connect this pin with a 1 μ F capacitor to V_{SS} and a 1 $M\Omega$ resistor to V_{CC} . If this function is not used V_{PP} may be tied to V_{CC} . This pin was V_{BB} on the 8X9X-90 parts and is the programming voltage on EPROM part.
XTAL1	Input of the oscillator inverter and of the internal clock generator.
XTAL2	Output of the oscillator inverter.
CLKOUT	Output of the internal clock generator. The frequency of CLKOUT is ½ the oscillator frequency. It has a 50% duty cycle.
RESET	Reset input to the chip. Input low for at least 4 state times to reset the chip. The subsequent low-to-high transition re- synchronizes CLKOUT and commences a 10-state-time sequence in which the PSW is cleared, a byte read from 2018H loads CCR, and a jump to location 2080H is executed. Input high for normal operation. RESET has an internal pullup.
BUSWIDTH	Input for buswidth selection. If CCR bit 1 is a one, this pin selects the bus width for the bus cycle in progress. If BUSWIDTH is a 1, a 16-bit bus cycle occurs. If BUSWIDTH is a 0 an 8-bit cycle occurs. If CCR bit 1 is a 0, the bus is always an 8-bit bus. This pin is the TEST pin on 8X9X-90 parts. Systems with TEST tied to V _{CC} do not need to change.

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PIN DESCRIPTIONS (Continued)

Symbol	Name and Function					
NMI	A positive transition causes a vector through 203EH.					
INST	Output high during an external memory read indicates the read is an instruction fetch. INST is valid throughout the bus cycle. INST is activated only during external memory accesses and output low for a data fetch.					
EA	EA must be equal to a TTL-low to cause address locations 2000H through 3FFFH to be directed to off-chip memory.					
ALE/ADV	Address Latch Enable or Address Valid output, as selected by CCR. Both pin options provide a latch to demultiplex the address from the address/data bus. When the pin is ADV, it goes inactive high at the end of the bus cycle. ADV can be used as a chip select for external memory. ALE/ADV is activated only during external memory accesses.					
RD	Read signal output to external memory. $\overline{\text{RD}}$ is activated only during external memory reads.					
WR/WRL	Write and Write Low output to external memory, as selected by the CCR. WR will go low for every external write, while WRL will go low only for external writes where an even byte is being written. WR/WRL is activated only during external memory writes.					
BHE/WRH	Bus High Enable or Write High output to external memory, as selected by the CCR. $\overline{BHE}=0$ selects the bank of memory that is connected to the high byte of the data bus. $A0=0$ selects the bank of memory that is connected to the low byte of the data bus. Thus accesses to a 16-bit wide memory can be to the low byte only ($A0=0$, $\overline{BHE}=1$), to the high byte only ($A0=1$, $\overline{BHE}=0$), or both bytes ($A0=0$, $\overline{BHE}=0$). If the \overline{WRH} function is selected, the pin will go low if the bus cycle is writing to an odd memory location. $\overline{BHE}/\overline{WRH}$ is valid only during 16-bit external memory write cycles.					
READY	Ready input to lengthen external memory cycles, for interfacing to slow or dynamic memory, or for bus sharing. If the pin is high, CPU operation continues in a normal manner If the pin is low prior to the falling edge of CLKOUT, the memory controller goes into a wait mode until the next positive transition in CLKOUT occurs with READY high. When the external memory is not being used, READY has no effect. Internal control of the number o wait states inserted into a bus cycle held not ready is available through configuration of CCR.					
HSI	Inputs to High Speed Input Unit. Four HSI pins are available: HSI.0, HSI.1, HSI.2, and HSI.3. Two of them (HSI.2 and HSI.3) are shared with the HSO Unit.					
HSO	Outputs from High Speed Output Unit. Six HSO pins are available: HSO.0, HSO.1, HSO.2, HSO.3, HSO.4, and HSO.5. Two of them (HSO.4 and HSO.5) are shared with the HSI Unit					
Port 0	8-bit high impedance input-only port. Three pins can be used as digital inputs and/or as analog inputs to the on-chip A/D converter.					
Port 1	8-bit quasi-bidirectional I/O port.					
Port 2	8-bit multi-functional port. All of its pins are shared with other functions in the M80C196KB					
Ports 3 and 4	8-bit bi-directional I/O ports with open drain outputs. These pins are shared with the multiplexed address/data bus which has strong internal pullups.					



Instruction Summary

Mnemonic	Operands	perands Operation (Note 1)	Flags						Notes
			Z	N	С	V	VT	ST	
ADD/ADDB	2	D ← D + A	-	-	w	10	1	-	
ADD/ADDB	3	D ← B + A	100	100	-	100	1	100	
ADDC/ADDCB	2	$D \leftarrow D + A + C$	1	-	-	~	1	_	
SUB/SUBB	2	D ← D − A	-	10	10	10	1	_	
SUB/SUBB	3	D ← B − A	-	-	-	-	1		-1150
SUBC/SUBCB	2	$D \leftarrow D - A + C - 1$	1	-	10	10	1	1	
CMP/CMPB	2	D – A	-	-	10	-	1	3-3	
MUL/MULU	2	D,D + 2 ← D × A	_	-	-	-	3		2
MUL/MULU	3	D,D + 2 ← B × A	_	-	-	7.44 S	_	_	2
MULB/MULUB	2	D,D + 1 ← D × A	-	=	-	-	_	-	3
MULB/MULUB	3	D,D + 1 ← B × A	n <u>-</u> si	_	-	_	_	_	3
DIVU	2	$D \leftarrow (D,D+2)/A,D+2 \leftarrow remainder$	-			10	1		2
DIVUB	2	$D \leftarrow (D,D+1)/A,D+1 \leftarrow remainder$		-	20-0	-	1	_	3
DIV	2	$D \leftarrow (D,D+2)/A,D+2 \leftarrow remainder$		_	_	_	<u>†</u>	_	
DIVB	2	$D \leftarrow (D,D+1)/A,D+1 \leftarrow remainder$		-	-	м	1	-	7
AND/ANDB	2	D ← DANDA	10	10	0	0	-	_	
AND/ANDB	3	D ← B AND A	_	1	0	0			
OR/ORB	2	D ← DORA	w	u	0	0	8-8	-	
XOR/XORB	2	D ← D (ecxl. or) A	<u>u</u>	10	0	0	-	_	
LD/LDB	2	D ← A	_			_	_	_	
ST/STB	2	A ← D	-	_	-	_	-	_	
LDBSE	2	$D \leftarrow A; D + 1 \leftarrow SIGN(A)$	-		_		_	-	3,4
LDBZE	2	$D \leftarrow A; D+1 \leftarrow 0$	_	_	_		_	_	3,4
PUSH	1	SP ← SP - 2; (SP) ← A		_	-	_	_	_	0,1
POP	1	A ← (SP); SP + 2			-	_		_	
PUSHF	0	$SP \leftarrow SP - 2$; $(SP) \leftarrow PSW$; $PSW \leftarrow 0000H$; $I \leftarrow 0$	0	0	0	0	0	0	
POPF	0	PSW ← (SP); SP ← SP + 2; I ← μ	_	-	_	_	_	_	
SJMP	1	PC ← PC + 11-bit offset	_	_	_	_	_		5
LJMP	1	PC ← PC + 16-bit offset	_	_	_	_	_	_	5
BR[indirect]	1	PC ← (A)	-1	_	_	_	_	_	
SCALL	1	$SP \leftarrow SP - 2;$ $(SP) \leftarrow PC; PC \leftarrow PC + 11-bit offset$	-	-	-	-	-	-	5
LCALL	1	$SP \leftarrow SP - 2$; $(SP) \leftarrow PC$; $PC \leftarrow PC + 16$ -bit offset	22	12	-	-	-	-	5



Instruction Summary (Continued)

Mnemonic	Operands	Operation (Note 1)			Fla	198			Notes
Mnemonic	Operanus	Operation (Note 1)	Z	N	С	٧	VT	ST	
RET	0	PC ← (SP); SP ← SP + 2	-	-	-	-	-	-	
J (conditional)	1	PC ← PC + 8-bit offset (if taken)	-	-	-	-	-	-	5
JC	1	Jump if C = 1	-	-	-	-	-	-	5
JNC	1	jump if C = 0	-	-	-	_	-	-	5
JE .	1	jump if Z = 1	-	-	-	-		-	5
JNE	1	Jump if Z = 0	-	-	-	-	-	-	5
JGE	1	Jump if N = 0	-	-	-	_	_	-	5
JLT	1	Jump if N = 1	-	-	-	-	·	-	5
JGT	1	Jump if $N = 0$ and $Z = 0$	-	-	-	Н	-	-	5
JLE	1	Jump if $N = 1$ or $Z = 1$	-	_	_	_	_	-	5
JH	1	Jump if C = 1 and Z = 0	-	-	-	-	-	-	5
JNH	1	Jump if C = 0 or Z = 1	-	-	-	-	-	-	5
JV	1	Jump if V = 0	-	1	-	-	\[-\]		5
JNV	1	Jump if V = 1	-	-	=	-	-	-	5
JVT	1	Jump if VT= 1; Clear VT	-	-	-	-	0	-	5
JNVT	1	Jump if VT = 0; Clear VT		-	-	-	0	-	5
JST	1	Jump if ST = 1	-	-	-	-	-	-	5
JNST	1	Jump if ST = 0	-	-	-	-	-	-	5
JBS.	3	Jump if Specified Bit = 1	-	-	-	-	-	-	5,6
JBC	3	Jump if Specified Bit = 0	-	-	-	-	_	-	5,6
DJNZ/ DJNZW	1	$D \leftarrow D - 1;$ If $D \neq 0$ then PC \leftarrow PC + 8-bit offset	-	-	-	-	-	-	5
DEC/DECB	1	D ← D − 1	-	10	1	-	1	-	
NEG/NEGB	1	D ← 0 − D	1	10	"	-	1	-	
INC/INCB	1	D ← D + 1	10	10	-	10	1	-	
EXT	1	D ← D; D + 2 ← Sign (D)	10	"	0	0	-	-	2
EXTB	1	D ← D; D + 1 ← Sign (D)	-	"	0	0	-	-	3
NOT/NOTB	1	D ← Logical Not (D)	10	10	0	0	-	-	
CLR/CLRB	1	D ← 0	1	0	0	0	-	-	
SHL/SHLB/SHLL	2	C ← msbisb ← 0	10	"	"	10	1	-	7
SHR/SHRB/SHRL	2	0 → msblsb → C	-	-	-	0	-	-	7
SHRA/SHRAB/SHRAL	2	msb → msblsb → C	10	10	10	0	-	"	7
SETC	0	C ← 1	-	-	1	1=	-	-	S.
CLRC	0	C ← 0	-	-	0	· ;	-	-	



Instruction Summary (Continued)

Mnemonic	Operands	Operation (Note 1)			F	lags			Notes
	(S)//		Z	N	С	C V VT ST		ST	Notes
CLRVT	0	VT ← 0	-	_	-	3-3	0	220	
RST	0	PC ← 2080H	0	0	0	0	0	0	8
DI	0	Disable All Interupts (I ← 0)	2.50	_	-	-	-		
EI	0	Enable All Interupts (I ← 1)	-	_	_	_		_	
NOP	0	PC ← PC + 1	-	2278	-	-	-	_	
SKIP	0	PC ← PC + 2	_	_	_	-	_	_	ii) e
NORML	2	Left shift till msb = 1; D ← shift count	10	~	0	_	_		7
TRAP	0	$SP \leftarrow SP - 2;$ $(SP) \leftarrow PC; PC \leftarrow (2010H)$	-	=8	-	-	-	-	9
PUSHA	1	$SP \leftarrow SP-2; (SP) \leftarrow PSW;$ $PSW \leftarrow 0000H; SP \leftarrow SP-2;$ $(SP) \leftarrow IMASK1/WSR; IMASK1 \leftarrow 00H$	0	0	0	0	0	0	
POPA	1	IMASK1/WSR \leftarrow (SP); SP \leftarrow SP+2 PSW \leftarrow (SP); SP \leftarrow SP+2	~	-	_	-	-	-	
IDLPD	1	IDLE MODE IF KEY=1; POWERDOWN MODE IF KEY =2; CHIP RESET OTHERWISE	-	-	-	-	-	-	
CMPL	2	D-A	~	10	-	~	1	-	
вмоч	2	[PTR_Hi]+ ← [PTR_LOW]+; UNTIL COUNT=0	-	-	-	-		-	

- If the mnemonic ends in "B" a byte operation is performed, otherwise a word operation is done. Operands D, B, and A
 must conform to the alignment rules for the required operand type. D and B are locations in the Register File; A can be located anywhere in memory.

 2. D,D + 2 are consecutive WORDS in memory; D is DOUBLE-WORD aligned.

 3. D,D + 1 are consecutive BYTES in memory; D is WORD aligned.

- 4. Changes a byte to word.
- 5. Offset is a 2's complement number.
- 6. Specified bit is one of the 2048 bits in the register file.
- 7. The "L" (Long) suffix indicates double-word operation.
 8. Initiates a Reset by pulling RESET low. Software should re-initialize all the necessary registers with code starting at 2080H.
 9. The assembler will not accept this mnemonic.



Instruction Execution State Times (Minimum) (1)

	DIRECT	IMMED	INDIRE	СТ	INDE	INDEXED		
MNEMONIC	DIRECT	IMMED	NORMAL*	A-INC*	SHORT*	LONG*		
ADD (3-op)	5	6	7/10	8/11	7/10	8/11		
SUB (3-op)	5	6	7/10	8/11	7/10	8/11		
' ' '	4	5	6/8	7/9	6/8	7/9		
ADD (2-op)	4	5	6/8	7/9	6/8	7/9		
SUB (2-op)	4	5	6/8	7/9	6/8	7/9		
ADDC	4	5	6/8	7/9	6/8	7/9		
SUBC	4	5	6/8	7/9	6/8	7/9		
CMP		5	7/10	8/11	7/10	8/11		
ADDB (3-op)	5		7/10	8/11	7/10	8/11		
SUBB (3-op)	5	5	6/8	7/9	6/8	7/9		
ADDB (2-op)	4	4		7/9	6/8	7/9		
SUBB (2-op)	4	4	6/8		6/8	7/9		
ADDCB	4	4	6/8	7/9		7/9		
SUBCB	4	4	6/8	7/9	6/8	7/9		
CMPB	4	4	6/8	7/9	6/8			
MUL (3-op)	16	17	18/21	19/22	19/22	20/23		
MULU (3-op)	14	15	16/19	17/19	17/20	18/21		
MUL (2-op)	16	17	18/21	19/22	19/22	20/23		
MULU (2-op)	14	15	16/19	17/19	17/20	18/21		
DIV	26	27	28/31	29/32	29/32	30/33		
DIVU	24	25	26/29	27/30	27/30	28/31		
MULB (3-op)	12	12	14/17	15/18	15/18	16/19		
MULUB (3-op)	10	10	12/15	13/15	12/16	14/17		
	12	12	14/17	15/18	15/18	16/19		
MULB (2-op)	10	10	12/15	13/15	12/16	14/17		
MULUB (2-op)	18	18	20/23	21/24	21/24	22/25		
DIVB DIVUB	16	16	18/21	19/22	19/22	20/23		
	5	6	7/10	8/11	7/10	8/11		
AND (3-op)	4	5	6/8	7/9	6/8	7/9		
AND (2-op)	4	5	6/8	7/9	6/8	7/9		
OR (2-op)	1	5	6/8	7/9	6/8	7/9		
XOR	4	5	7/10	8/11	7/10	8/11		
ANDB (3-op)	5		6/8	7/9	6/8	7/9		
ANDB (2-op)	4	4 4	6/8	7/9	6/8	7/9		
ORB (2-op)	4 4	4	6/8	7/9	6/8	7/9		
XORB		5	5/8	6/8	6/9	7/10		
LD/LDB	4			6/8	6/9	7/10		
ST/STB	4	5	5/8	6/8	6/9	7/10		
LDBSE	4	4	5/8		6/9	7/10		
LDBZE	4	4	5/8	6/8				
BMOV		6+8 per w	ord	6	+ 11/14 per v			
PUSH (int stack)	6	7	9/12	10/13	10/13	11/14		
POP (int stack)	8		10/12	11/13	11/13	12/14		
PUSH (ext stack)	8	9	11/14	12/15	12/15	13/16		
POP (ext stack)	11	_	13/15	14/16	14/16	15/17		

^{*}Times for (Internal/External) Operands

NOTE:

1. Execution times for instructions accessing external data memory may be one to two states higher depending on the instruction stream being executed. In sixteen bit mode, the minimum execution state times apply for instructions accessing internal register space. Execution times do not reflect eight bit mode or insertion of wait states.

Instruction Execution State Times (Continued)

MNEMONIC		MNEMONIC	
PUSHF (int stack) POPF (int stack) PUSHA (int stack) POPA (int stack)	6 7 12 12	PUSHF (ext stack) POPF (ext stack) PUSHA (ext stack) POPA (ext stack)	8 10 18 18
TRAP (int stack) LCALL (int stack) SCALL (int stack) RET (int stack)	16 11 11 11	TRAP (ext stack) LCALL (ext stack) SCALL (ext stack) RET (ext stack)	18 13 13 14
CMPL CLR/CLRB NOT/NOTB NEG/NEGB	7 3 3 3	DEC/DECB EXT/EXTB INC/INCB	3 4 3
LJMP SJMP BR (indirect) JNST, JST JNH, JH JGT, JLE JNC, JC JNVT, JVT JNV, JV JGE, JLT JNE, JE JBC, JBS	4/8 jump no 4/8 jump no 4/8 jump no 4/8 jump no 4/8 jump no 4/8 jump no 4/8 jump no	ot taken/jump taken	
DJNZ DJNZW	5/9 jump no	t taken/jump taken t taken/jump taken	
NORML SHRL SHLL SHRAL SHR/SHRB SHL/SHLB SHRA/SHRAB	8 + 1 per sh 7+ 1 per sh 7 + 1 per sh 7 + 1 per sh 6 + 1 per sh 6 + 1 per sh	nift (9 for 0 shift) ift (8 for 0 shift) nift (7 for 0 shift) nift (7 for 0 shift) nift (7 for 0 shift)	
CLRC SETC DI EI CLRVT NOP RST SKIP IDLPD	2 2 2 2 2 2 2 15 (includes	fetch of configuration byte) key/improper key)	



MEMORY MAP

EXTERNAL MEMORY OR I/O	4000H
INTERNAL ROM/EPROM OR EXTERNAL MEMORY	2080H
RESERVED	2040H
UPPER 8 INTERRUPT VECTORS	2030H
ROM/EPROM SECURITY KEY*	2020H
RESERVED	2020H
CHIP CONFIGURATION BYTE	2019H
RESERVED	2016H
LOWER 8 INTERRUPT VECTORS	201411
PLUS 2 SPECIAL INTERRUPTS	2000H
PORT 3 AND PORT 4	1FFEH
EXTERNAL MEMORY OR I/O	0100H
INTERNAL DATA MEMORY - REGISTER FILE (STACK POINTER, RAM AND SFRS)	
EXTERNAL PROGRAM CODE MEMORY	0000H

M80C196KB INTERRUPTS

Number	Source	Vector Location	Priority
INT15	NMI	203EH	15
INT14	HSI FIFO Full	203CH	14
INT13	EXTINT Pin	203AH	13
INT12	TIMER2 Overflow	2038H	12
INT11	TIMER2 Capture	2036H	11
INT10	4th Entry into HSI FIFO	2034H	10
INT09	RI	2032H	9
INT08	TI	2030H	8
SPECIAL	Unimplemented Opcode	2012H	N/A
SPECIAL	Trap	2010H	N/A
INT07	EXTINT	200EH	7
INT06	Serial Port	200CH	6
INT05	Software Timer	200AH	5
INT04	HSI.0 Pin	2008H	4
INT03	High Speed Outputs	2006H	3
INT02	HSI Data Available	2004H	2
INT01	A/D Conversion Complete	2002H	1
INT00	Timer Overflow	2000H	0

19H	STACK POINTER	19H	STACK POINTER
18H	STACK POINTER	18H	AT A COMMENSA POSTER
17H	*IOS2	17H	PWM_CONTROL
16H	IOS1	16H	IOC1
15H	IOS0	15H	IOC0
14H	*WSR	14H	*WSR
13H	*INT_MASK 1	13H	*INT_MASK 1
12H	*INT_PEND 1	12H	*INT_PEND 1
1111	*SP_STAT	11H	*SP_CON
10H	PORT2	10H	PORT2
OFH	PORT1	0FH	PORT1
0EH	PORT0	0EH	BAUD RATE
ODH	TIMER2 (HI)	ODH	TIMER2 (HI)
OCH	TIMER2 (LO)	осн	TIMER2 (LO)
овн	TIMER1 (HI)	0BH	*IOC2
OAH	TIMER1 (LO)	OAH	WATCHDOG
09Н	INT_PENDING	09Н	INT_PENDING
DBH	INT_MASK	08H	INT_MASK
07H	SBUF(RX)	07H	SBUF(TX)
06H	HSI_STATUS	06H	HSO_COMMAND
05H	HSL_TIME (HI)	05H	HSO_TIME (HI)
04H	HSI_TIME (LO)	04H	HSO_TIME (LO)
03H	AD_RESULT (HI)	03H	HSI_MODE
02H	AD_RESULT (LO)	02H	AD_COMMAND
01H	ZERO REG (HI)	01H	ZERO REG (HI)
00H	ZERO REG (LO)	00н [ZERO REG (LO)
Jon	WHEN READ	wsr = 0	WHEN WRITTEN

RESERVED (1)
RESERVED (1)
*T2 CAPTURE (HI)
*T2 CAPTURE (LO)

WSR = 15

OTHER SFRS IN WSR
15 BECOME READABLE
IF THEY WERE WRITABLE
IN WSR = 0 AND WRITABLE
IN WSR = 0

*NEW OR CHANGED REGISTER FUNCTION

NOTE:

1. Reserved registers should not be written.



IOC2 (0BH)

USING THE ALTERNATE REGISTER WINDOW (WSR = 15)

I/O register expansion on the new CHMOS members of the MCS-96 family has been provided by making two register windows available. Switching between these windows is done using the Window Select Register (WSR). The PUSHA and POPA instructions can be used to push and pop the WSR and second interrupt mask when entering or leaving interrupts, so it is easy to change between windows.

On the M80C196KB only Window 0 and Window 15 are active. Window 0 is a true superset of the standard 8096 SFR space, while Window 15 allows the read-only registers to be written and write-only registers to be read. The only major exception to this is the Timer2 register which is the Timer2 capture register in Window 15. The writeable register for Timer2 is in Window 0. There are also some minor changes and cautions. The descriptions of the registers which have different functions in Window 15 than in Window 0 are listed below:

AD_COMMAND (02H) - Read the last written command AD_RESULT (02H, 03H) — Write a value into the result register HSI_MODE (03H) - Read the value in HSI_MODE HSI__TIME (04H,05H) - Write to FIFO Holding register

HSO_TIME (04H,05H) - Read the last value placed in the holding register

HSI_STATUS (06H) - Write to status bits but not to HSI pin bits. (Pin bits are 1,3,5,7).

HSO_COMMAND (06H) — Read the last value placed in the holding register

SBUF(RX) (07H) - Write a value into the receive buffer

SBUF(TX) (07H) - Read the last value written to the transmit buffer WATCHDOG(0AH) - Read the value in the upper byte of the WDT

TIMER1 (0AH,0BH) - Write a value to Timer1

TIMER2 (0CH,0DH) - Read/Write the Timer2 capture register.

Note that Timer2 read/write is done with WSR = 0. - Last written value is readable, except bit 7 (note 1)

BAUD_RATE (0EH) - No function, cannot be read

PORTO (OEH) - No function, no output drivers on the pins. Register reserved.

PORT1 - IOPORT1 cannot be read or written in Window 15. Register reserved. SP_STAT (11H) - Set the status bits, TI and RI can be set, but it will not cause an interrupt

SP_CON (11H) - Read the current control byte

IOS0 (15H) Writing to this register controls the HSO pins. Bits 6 and 7 are inactive for writes.

IOC0 (15H) - Last written value is readable, except bit 1 (note 1)

- Writing to this register will set the status bits, but not cause interrupts. Bits 6 and IOS1 (16H)

7 are not functional

IOC1 (16H) Last written value is readable

IOS2 (17H) - Writing to this register will set the status bits, but not cause interrupts.

PWM_CONTROL (17H) — Read the duty cycle value written to PWM_CONTROL

NOTE:

1. IOC2.7 (CAM CLEAR) and IOC0.1 (T2RST) are not latched and will read as a 1 (precharged bus) .

Being able to write to the read-only registers and vice-versa provides a lot of flexibility. One of the most useful advantages is the ability to set the timers and HSO lines for initial conditions other than zero.

Reserved registers may be used for testing as future features. Do not write to these registers. Read from reserved registers will return indeterminate values.



SFR BIT SUMMARY

A summary of the SFRs which control I/O functions has been included in this section. The summary is separated into a list of those SFRs which have changed on the M80C196KB and a list of those which have remained almost the same.

The following M80C196KB SFRs are different than those on the M8096BH: (The Read and Write comments indicate the register's function in Window 0 unless otherwise specified.)

SBUF(TX):

Now double buffered

07h

write

BAUD RATE:

Uses new Baud Rate Values

0Eh write

SP_STAT:

7	6	5	4	3	2	1	0
RB8/ RPE	RI	TI	FE	TXE	OE	X	Х

11h read RPE:

Receive Parity Error

RI:

Receive Indicator

TI:

Transmit Indicator

FE:

Framing Error

TXE:

Transmitter Empty

OE:

Receive Overrun Error

IPEND1: IMASK1:

7	6	5	4	3	2	1	0
NMI	FIFO	EXT	T2 OVF	T2 CAP	HSI4	RI	TI

12h,13h read/write NMI:

Non-Maskable Interrupt (set to 0 for future compatibility)

FIFO FULL: HSIO FIFO full

EXTINT:

External Interrupt Pin

T2OVF:

Timer2 Overflow

T2CAP:

Timer2 Capture

HSI4:

HSI has 4 or more entries in FIFO

RI:

Receive Interrupt

TI:

Transmit Interrupt



WSR:

7	6	5	4	3	2	1	0
0	0	0	0	W	W	w	w

14h read/write

WWWW = 0: SFRs function like a superset of M8096 SFRs

WWWW=14: PPW register

WWWW = 15: Exchange read/write registers WWWW=OTHER: Undefined, do not use

0000:

These bits must always be written as zeros to provide compatibility

with future products.

IOS2:

7	6	5	4	3	2	1	0
START A2D	T2 RESET	HSO.5	HSO.4	HSO.3	HSO.2	HSO.1	HSO.0

17h read

Indicates which HSO event occured

START A2D:

HSO_CMD 15, start A to D

T2RESET:

HSO_CMD 14, Timer 2 reset

HSO.0-5:

Output pins HSO.0 through HSO.5

IOC2:

7	6	5	4	3	2	1	0
	ENA LOCK	T2ALT INT	A2D CPD	x	SLOW	T2UD ENA	

0Bh write

CLEAR_CAM: Clear Entire CAM

ENA_LOCK: Enable lockable CAM entry feature

T2ALT INT: A2D_CPD:

Enable T2 Alternate Interrupt at 8000H

Clock Prescale Disable for low XTAL frequency (A to D conversion in fewer state times)

X:

Set to 0

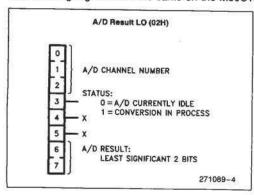
SLOW_PWM: Turn on divide by 2 Prescaler on PWM

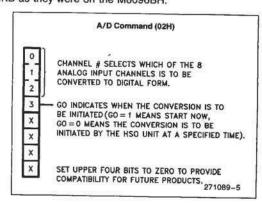
T2UD ENA:

Enable Timer 2 as up/down counter

FAST_T2EN: Enable Fast increment of T2; once per state time.

The following registers are the same on the M80C196KB as they were on the M8096BH:

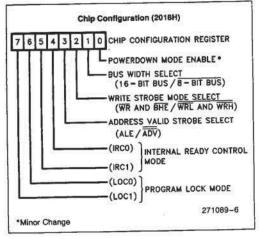


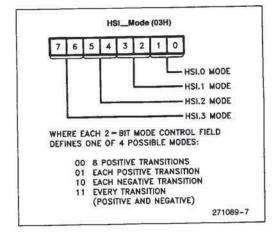


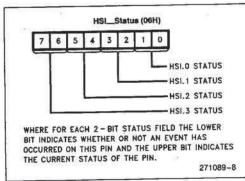
4826175 0169941 315

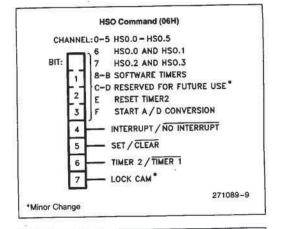
M80C196KB

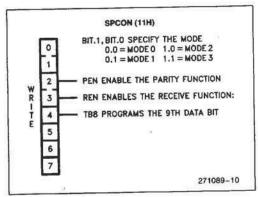


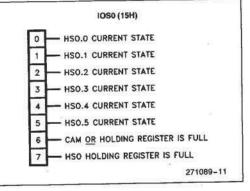




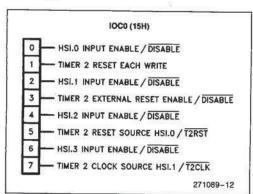


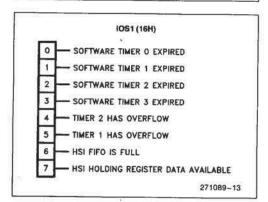


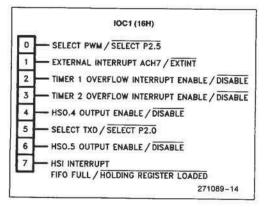












Port 2 Multiple Functions

Pin	Func.	Alternative Function	Control Reg.
2.0	Output	TXD (Serial Port Transmit)	IOC1.5
2.1	Input	RXD (Serial Port Receive)	SPCON.3
2.3	Input	T2CLK (Timer2 Clock & Baud)	IOC0.7
2.4	Input	T2RST (Timer2 Reset)	IOC0.5
2.5	Output	PWM Output	IOC1.0
2.6	QBD*	Timer2 up/ down select	IOC2.1
2.7	QBD*	Timer2 Capture	N/A

*QBD = Quasi-bidirectional

Baud Rate Calculations

Asynchronous Modes 1, 2 and 3:

$$Baud_Reg = \frac{XTAL1}{Baud Rate \times 16} - 1 OR \frac{T2CLK}{Baud Rate \times 8}$$

Synchronous Mode 0:

$$Baud_Reg = \frac{XTAL1}{Baud\ Rate \times 2} - 1 \ OR \ \frac{T2CLK}{Baud\ Rate}$$

Baud Rates and Baud Register Values

Baud	XTAL Frequency							
Rate	8.0 MHz		10.0 MHz		12.0 MHz			
300	1666	-0.02	2082	0.02	2499	0.00		
1200	416	-0.08	520	-0.03	624	0.00		
2400	207	0.16	259	0.16	312	-0.16		
4800	103	-0.16	129	0.16	155	0.16		
9600	51	-0.16	64	0.16	77	0.16		
19.2K	25	0.16	32	1.40	38	0.16		

Baud Register Value/% Error

A maximum baud rate of 750 Kbaud is available in the asynchronous modes with 12 MHz on XTAL1. The synchronous mode has a maximum rate of 3.0 Mbaud with a 12 MHz clock. Location 0EH is the Baud Register. It is loaded sequentially in two bytes, with the low byte being loaded first. This register may not be loaded with zero in serial port Mode 0.

NOTE:

The maximum T2CLK rate is 3 MHz when used to set the baud rate.



ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Case Temperature under Bias	55°C to +125°C
Storage Temperature	65°C to +150°C
Voltage On Any Pin to Vss	0.5V to +7.0V
Power Dissipation	1.5W

NOTICE: This data sheet contains preliminary information on new products in production. The specifications are subject to change without notice. Verify with your local Intel Sales office that you have the latest data sheet before finalizing a design.

*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

OPERATING CONDITIONS

MIL CTD-002

T-21D-000				2-08/8/09/02
Symbol	Description	Min	Max	Units
To	Case Temperature (Instant On)	-55	+ 125	°C
V _{CC}	Digital Supply Voltage	4.50	5.50	٧
V _{REF}	Analog Supply Voltage	4.50	5.50	V
fosc	Oscillator Frequency	3.5	12	MHz

Military Temperature (MTO)

Symbol	Description	Min	Max	Units
T _C	Case Temperature (Instant On)	-55	+125	°C
V _{CC}	Digital Supply Voltage	4.50	5.50	٧
V _{REF}	Analog Supply Voltage	4.50	5.50	V
fosc	Oscillator Frequency	3.5	12	MHz

NOTE: ANGND and V_{SS} should be nominally at the same potential.

DC Characteristics (Over Specified Operating Conditions)

Symbol	Description	Min	Max	Units	Comments
VIL	Input Low Voltage	-0.5	0.8	٧	
VIH	Input High Voltage (Note 1)	0.2 V _{CC} + 1.0	Vcc	V	
V _{IH1}	Input High Voltage on XTAL 1	0.7 V _{CC}	Vcc	V	
V _{IH2}	Input High Voltage on RESET	2.2	Vcc	V	W-55
V _{OL}	Output Low Voltage		0.3 0.45 1.5	V V	I _{OL} = 200 μA I _{OL} = 3.2 mA I _{OL} = 7 mA
V _{OH}	Output High Voltage (Standard Outputs) (Note 2)	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5		V V	$I_{OH} = -200 \mu A$ $I_{OH} = -3.2 \text{ mA}$ $I_{OH} = -7 \text{ mA}$
V _{OH1}	Output High Voltage (Quasi-bidirectional Outputs) (Note 3)	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5		> > >	$I_{OH} = -10 \mu A$ $I_{OH} = -30 \mu A$ $I_{OH} = -60 \mu A$

NOTES:

1. All pins except RESET and XTAL1.
2. Standard Outputs include AD0-15, RD, WR, ALE, BHE, INST, HSO pins, PWM/P2.5, CLKOUT, RESET, Ports 3 and 4, TXD/P2.0, and RXD (in serial mode 0). The V_{OH} specification is not valid for RESET. Ports 3 and 4 are open-drain outputs.
3. QBD (Quasi-bidirectional) pins include Port 1, P2.6 and P2.7.



DC Characteristics (Over Specified Operating Conditions) (Continued)

Symbol	Description	Min	Max	Units	Comments
ILI	Input Leakage Current (Std. Inputs) (Note 4)		±10	μΑ	0 < V _{IN} < V _{CC} - 0.3V
ILH .	Input Leakage Current ()		±7	mA	0 < V _{IN} < V _{REF}
I _{TL}	1 to 0 Transition Current (QBD Pins) (Note 3)		-800	μА	V _{IN} = 2.0V
1 _{IL}	Logical 0 Input Current (QBD Pins) (Note 3)		-50	μΑ	V _{IN} = 0.45V
I _{IL1}	Logical 0 Input Current in Reset (Note 5) (ALE, RD, WR, BHE, INST, P2.0)		-850	μΑ	V _{IN} = 0.45 V
Icc	Active Mode Current in Reset		60	mA	XTAL1 = 12 MHz
IREF	A/D Converter Reference Current		5	mA	$V_{CC} = V_{PP} = V_{REF} = 5.5V$
IDLE	Idle Mode Current		25	mA	
lcc1	Active Mode Current		30	mA	XTAL1 = 3.5 MHz
I _{PD}	Powerdown Mode Current		50	μА	V _{CC} = V _{PP} = V _{REF} = 5.5V, XTAL1 = 12 MHz
R _{RST}	Reset Pullup Resistor	6K	50K	Ω	
Cs	Pin Capacitance (Any Pin to V _{SS})		10	pF	f _{TEST} = 1.0 MHz

NOTES:

(Notes apply to all specifications)

2. Standard Outputs include AD0-15, AD, WR, ALE, BHE, INST, HSO pins, PWM/P2.5, CLKOUT, RESET, Ports 3 and 4, 2. Standard Outputs Include ADD-15, HD, WH, ALE, BHE, INS1, HSO pins, PWM/P2.5, CLROU1, HESE1, Ports 3 and 4, TXD/P2.0, and RXD (in serial mode 0). The VoH specification is not valid for RESET. Ports 3 and 4 are open-drain outputs.

3. QBD (Quasi-bidirectional) pins include Port 1, P2.6 and P2.7.

4. Standard Inputs include HSI pins, EA, READY, BUSWIDTH, NMI, RXD/P2.1, EXTINT/P2.2, T2CLK/P2.3, and T2RST/

5. Holding these pins below V_{IH} in Reset may cause the part to enter test modes.

6. Maximum current per pin must be externally limited to the following values if V_{OL} is held above 0.45V or V_{OH} is held below $V_{CC} - 0.7V$:

IOL on Output pins: 10 mA

IOH on quasi-bidirectional pins: self limiting

 I_{OH} on Standard Output pins: 10 mA 7. Maximum current per bus pin (data and control) during normal operation is ± 3.2 mA.

7. Maximum current per bus pin (data and control) during normal operation is ±3.

8. During normal (non-transient) conditions the following total current limits apply:

Port 1, P2.6

HSO, P2.0, RXD, RESET
P2.5, P2.7, WR, BHE
IoL: 29 mA
IoH: 26 mA
IoH: 11 mA
IoH: 52 mA
IoH: 52 mA
IoH: 52 mA
IoH: 52 mA
IoH: 13 mA

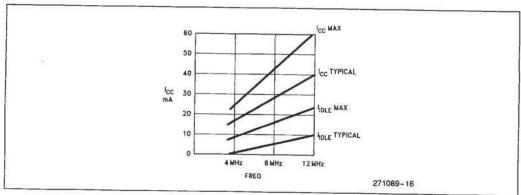


Figure 4. I_{CC} and I_{IDLE} vs Frequency



AC Characteristics (Over Specified Operating Conditions)
Test Conditions: Capacitive load on all pins = 100 pF, Rise and fall times = 10 ns, $f_{OSC} =$ 12 MHz

The system must meet these specifications to work with the M80C196KB:

Symbol	Description	Min	Max	Units	Notes
T _{AVYV}	Address Valid to READY Setup		2T _{OSC} - 85	ns	
T _{LLYV}	ALE Low to READY Setup M80C196KB		T _{OSC} - 75	ns	
Tylyh	Non READY Time	No up	per limit	ns	
T _{CLYX}	READY Hold after CLKOUT Low	0	T _{OSC} - 30	ns	(Note 1).
TLLYX	READY Hold after ALE Low	T _{OSC} - 15	2T _{OSC} - 40	ns	(Note 1)
TAVGV	Address Valid to Buswidth Setup		2T _{OSC} - 85	ns	
TLLGV	ALE Low to Buswidth Setup		T _{OSC} - 70	ns	
T _{CLGX}	Buswidth Hold after CLKOUT Low	0		ns	
T _{AVDV}	Address Valid to Input Data Valid M80C196KB		3T _{OSC} - 67	ns	
T _{RLDV}	RD Active to Input Data Valid M80C196KB	4	T _{OSC} - 23	ns	
T _{CLDV}	CLKOUT Low to Input Data Valid		T _{OSC} - 50	ns	
T _{RHDZ}	End of RD to Input Data Float		T _{OSC} - 20	ns	
T _{RXDX}	Data Hold after RD Inactive	0		ns	

NOTE:

If max is exceeded, additional wait states will occur.



$\begin{tabular}{ll} \bf AC & \bf Characteristics & (Over Specified Operating Conditions) & (Continued) \\ Test & \bf Conditions: & \bf Capacitive & load & on all pins = 100 pF, Rise and fall times = 10 ns, <math>f_{OSC} = 12 \ MHz \\ \hline \end{tabular}$

The M80C196KB will meet these specifications:

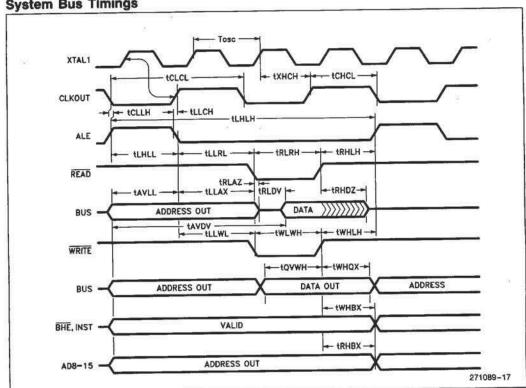
Symbol	Description	Min	Max	Units	Notes
FXTAL	Frequency on XTAL ₁ M80C196KB	3.5	12	MHz	
Tosc	I/F _{XTAL} M80C196KB	83	286	ns	
TXHCH	XTAL1 High to CLKOUT High or Low	20	110	ns	
TCLCL	CLKOUT Cycle Time	2T	osc	ns	
T _{CHCL}	CLKOUT High Period	T _{OSC} - 10	Tosc+10	ns	
TCLLH	CLKOUT Falling Edge to ALE Rising	-10	10	ns	
TLLCH	ALE Falling Edge to CLKOUT Rising	-15	15	ns	
TLHLH	ALE Cycle Time	4T ₀	osc	ns	
TLHLL	ALE High Period	T _{OSC} - 12	Tosc+12	ns	
TAVLL	Address Setup to ALE Falling Edge	T _{OSC} - 20		ns	
T _{LLAX}	Address Hold after ALE Falling Edge	T _{OSC} - 40		ns	
TLLAL	ALE Falling Edge to RD Falling Edge	T _{OSC} - 40		ns	100
TRLCL	RD Low to CLKOUT Falling Edge	4	25	ns	
T _{RLRH}	RD Low Period	T _{OSC} -5		ns	
TRHLH	RD Rising Edge to ALE Rising Edge	Tosc	T _{OSC} + 25	ns	(Note 2)
T _{RLAZ}	RD Low to Address Float		10	ns	
T _{LLWL}	ALE Falling Edge to WR Falling Edge	T _{OSC} - 10	100	ns	
T _{CLWL}	CLKOUT Low to WR Falling Edge	0	25	ns	
Tavwh	Data Stable to WR Rising Edge M80C196KB	T _{OSC} - 23		ns	196
T _{CHWH}	CLKOUT High to WR Rising Edge	-5	15	ns	
TWLWH	WR Low Period	T _{OSC} - 30		ns	
Twhax	Data Hold after WR Rising Edge	T _{OSC} - 15		ns	
TWHLH	WR Rising Edge to ALE Rising Edge	T _{OSC} - 15	T _{OSC} + 10	ns	(Note 2)
T _{WHBX}	BHE, INST HOLD after WR Rising Edge	T _{OSC} - 15	300	ns	,

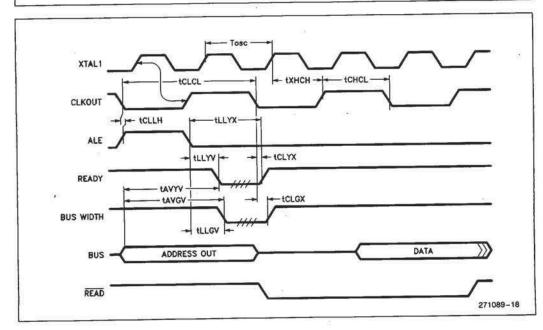
NOTE:

2. Assuming back-to-back bus cycles.







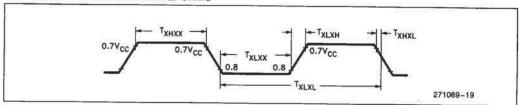




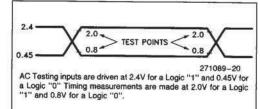
EXTERNAL CLOCK DRIVE

Symbol	Parameter	Min	Max	Units
1/T _{XLXL}	Oscillator Frequency M80C196KB	3.5	12.0	MHz
TXLXL	Oscillator Period M80C196KB	83	286	ns
T _{XHXX}	High Time	32		ns
T _{XLXX}	Low Time	32		ns
T _{XLXH}	Rise Time		10	ns
T _{XHXL}	Fall Time		10	ns

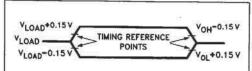
EXTERNAL CLOCK DRIVE WAVEFORMS



AC TESTING INPUT, OUTPUT WAVEFORMS



FLOAT WAVEFORMS



For Timing Purposes a Port Pin is no Longer Floating when a 100 mV change from Load Voltage Occurs and Begins to Float when a 100 mV change from the Loaded VoH/VoL Level occurs $I_{OL}/I_{OH} = \pm 15$ mA.

EXPLANATION OF AC SYMBOLS

Each symbol is two pairs of letters prefixed by "T" for time. The characters in a pair indicate a signal and its condition, respectively. Symbols represent the time between the two signal/condition points.

Conditions:

Z - Floating

X - No Longer Valid

Signals: H - High A - Address L - Low B - BHE V - Valid

C - CLKOUT D - DATA

L - ALE/ADV R - RD

W - WR/WRH/WRL X - XTAL1

G - Buswidth Y - READY



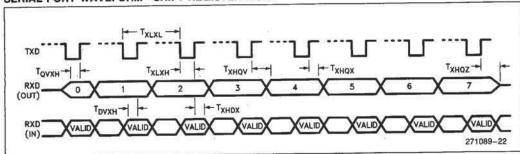
AC CHARACTERISTICS—SERIAL PORT—SHIFT REGISTER MODE

SERIAL PORT TIMING-SHIFT REGISTER MODE

Symbol	Parameter	Min	Max	Units
T _{XLXL}	Serial Port Clock Period (BRR ≥ 8002H)	6 T _{OSC}		ns
T _{XLXH}	Serial Port Clock Falling Edge to Rising Edge (BRR ≥ 8002H)	4 T _{OSC} - 50	4 T _{OSC} + 50	ns
T _{XLXL}	Serial Port Clock Period (BRR = 8001H)	4 Tosc		ns
T _{XLXH}	Serial Port Clock Falling Edge to Rising Edge (BRR = 8001H)	2 T _{OSC} - 50	2 T _{OSC} + 50	ns
T _{QVXH}	Output Data Setup to Clock Rising Edge	2 T _{OSC} -50		ns
T _{XHQX}	Output Data Hold after Clock Rising Edge	2 T _{OSC} -50		ns
T _{XHQV}	Next Output Data Valid after Clock Rising Edge		2 T _{OSC} + 50	ns
T _{DVXH}	Input Data Setup to Clock Rising Edge	T _{OSC} +50		ns
T _{XHDX}	Input Data Hold after Clock Rising Edge	0		ns
T _{XHQZ}	Last Clock Rising to Output Float		Tosc	ns

WAVEFORM-SERIAL PORT-SHIFT REGISTER MODE

SERIAL PORT WAVEFORM—SHIFT REGISTER MODE





A TO D CHARACTERISTICS

There are two modes of A/D operation: with or without clock prescaler. The speed of the A/D converter can be adjusted by setting a clock prescaler on or off. At high frequencies more time is needed for the comparator to settle. The maximum frequency with the clock prescaler disabled is 8 MHz. The conversion times with the prescaler turned on or off is shown in the table below.

The converter is ratiometric, so the absolute accuracy is directly dependent on the accuracy and

stability of V_{REF} . V_{REF} must be close to V_{CC} since it supplies both the resistor ladder and the digital section of the converter.

A/D CONVERTER SPECIFICATIONS

The specifications given below assume adherence to the Operating Conditions section of this data sheet. Testing is performed in Mode 2 with $V_{REF}=5.12V$ and 12 MHz on XTAL1.

Clock Prescaler On IOC2.4 = 0	Clock Prescaler Off IOC2.4 = 1	
Mode 0-158 States	Mode 2-91 States	
26.33 μs @ 12 MHz	22.75 μs @ 8 MHz	

A/D CHARACTERISTICS (Over Specified Operating Conditions)

Parameter	Typical*(1)	Minimum	Maximum	Units**	Notes
Resolution	2	256	1024 10	Levels Bits	
Absolute Error		0	±4	LSBs	
Full Scale Error	-0.5 ±0.5		1827n	LSBs	·
Zero Offset Error	±0.5			LSBs	
Non-Linearity		0	±4	LSBs	
Differential Non-Linearity		0	±2	LSBs	
Channel-to-Channel Matching		0	± 1	LSBs	07.
Repeatability	±0.25			LSBs	
Temperature Coefficients: Offset Full Scale Differential Non-Linearity	0.009 0.009 0.009			LSB/°C LSB/°C LSB/°C	
Off Isolation		-60		dB	2, 3
Feedthrough	-60			dB	2
V _{CC} Power Supply Rejection	-60	(- 1);		dB	2
Input Resistance		750	1.2K	Ω	
DC Input Leakage		0	3.0	μА	
Sample Time Slow Mode Fast Mode	15 8		1000	States States	4
Input Capacitance	3	U-SS -8801		pF	

NOTES:

- *An "LSB", as used here, has a value of approximately 5 mV.
- 1. These values are expected for most parts at 25°C but are not tested or guaranteed.
- 2. DC to 100 KHz.
- 3. Multiplexer Break-Before-Make Guaranteed.
- 4. One state = 167 ns at 12 MHz, 250 ns at 8 MHz.



A/D GLOSSARY OF TERMS

ABSOLUTE ERROR—The maximum difference between corresponding actual and ideal code transitions. Absolute Error accounts for all deviations of an actual converter from an ideal converter.

ACTUAL CHARACTERISTIC—The characteristic of an actual converter. The characteristic of a given converter may vary over temperature, supply voltage, and frequency conditions. An actual characteristic rarely has ideal first and last transition locations or ideal code widths. It may even vary over multiple conversions under the same conditions.

BREAK-BEFORE-MAKE—The property of multiplexer which guarantees that a previously selected channel will be deselected before a new channel is selected (e.g., the converter will not short inputs together).

CHANNEL-TO-CHANNEL MATCHING—The difference between corresponding code transitions of actual characteristics taken from different channels under the same temperature, voltage and frequency conditions.

CHARACTERISTIC—A graph of input voltage versus the resultant output code for an A/D converter. It describes the transfer function of the A/D convert-

CODE-The digital value output by the converter.

CODE TRANSITION—The point at which the converter changes from an output code of Q, to a code of Q+1. The input voltage corresponding to a code transition is defined to be that voltage which is equally likely to produce either of two adjacent codes.

CODE WIDTH—The voltage corresponding to the difference between two adjacent code transitions.

DC INPUT LEAKAGE—Leakage current to ground from an analog input pin.

DIFFERENTIAL NON-LINEARITY—The difference between the ideal and actual code widths of the terminal based characteristic.

FEEDTHROUGH—Attenuation of a voltage applied on the selected channel of the A/D Converter after the sample window closes.

FULL SCALE ERROR—The difference between the expected and actual input voltage corresponding to the full scale code transition.

IDEAL CHARACTERISTIC—A characteristic with its first code transition at $V_{IN}=0.5$ LSB, its last code transition at $V_{IN}=(V_{REF}-1.5$ LSB) and all code widths equal to one LSB.

INPUT RESISTANCE—The effective series resistance from the analog input pin to the sample capacitor.

LSB—Least Significant Bit: The voltage corresponding to the full scale voltage divided by 2ⁿ, where n is the number of bits of resolution of the converter. For an 8-bit converter with a reference voltage of 5.12V, one LSB is 20 mV. Note that this is different than digital LSBs, since an uncertainty of two LSB, when referring to an A/D converter, equals 40 mV. (This has been confused with an uncertainty of two digital bits, which would mean four counts, or 80 mV.)

NON-LINEARITY—The maximum deviation of code transitions of the terminal based characteristic from the corresponding code transitions of the ideal characteristic.

OFF-ISOLATION—Attenuation of a voltage applied on a deselected channel of the A/D converter. (Also referred to as Crosstalk.)

REPEATABILITY—The difference between corresponding code transitions from different actual characteristics taken from the same converter on the same channel at the same temperature, voltage and frequency conditions.

RESOLUTION—The number of input voltage levels that the converter can unambiguously distinguish between. Also defines the number of useful bits of information which the converter can return.

SAMPLE TIME—Begins when the sample capacitor is attached to a selected channel and ends when the sample capacitor is disconnected from the selected channel.

TEMPERATURE COEFFICIENTS—Change in the stated variable per degree centigrade temperature change. Temperature coefficients are added to the typical values of a specification to see the effect of temperature drift.

TERMINAL BASED CHARACTERISTIC—An actual characteristic which has been rotated and translated to remove zero offset and full scale error.

V_{CC} REJECTION—Attenuation of noise on the V_{CC} line to the A/D converter.

ZERO OFFSET—The difference between the expected and actual input voltage corresponding to the first code transition.



M80C196KB FUNCTIONAL DEVIATIONS

The M80C196KB has the following problems.

- The DJNZW instruction is guaranteed to be functional. The DJNZ (byte instruction) work around is no longer needed.
- The serial port only tolerates a +1.25%, -7.5% baud rate error between Transmitter and Receiver. If the serial port fails on the receiver, increase the baud rate.
- The HSI unit has two errata: one dealing with resolution and the other with first entries into the FIFO.

The HSI resolution is 9 states instead of 8 states. Events on the same line may be lost if they occur faster than once every 9 state times.

There is a mismatch between the 9 state time HSI resolution and the 8 state time timer. This causes one time value to be unused every 9 timer counts. Events may receive a time-tag one count later than expected because of this "skipped" time value.

If the first two events into an empty FIFO (not including the Holding Register) occur in the same internal phase, both are recorded with one timetag. Otherwise, if the second event occurs within 9 states after the first, its time-tag is one count later than the first's. If this is the "skipped" time value, the second event's time-tag is 2 counts later than the first's.

If the FIFO and Holding Register are empty, the first event will transfer into the Holding Register after 8 state times, leaving the FIFO empty again. If the second event occurs after this time, it will act as a new first event into an empty FIFO.

 The serial port Framing Error flag that failed to indicate an error if the bit preceding the stop bit is a 1 has been fixed.

CONVERTING FROM OTHER M8097 FAMILY PRODUCTS TO THE M80C196KB

The following list of suggestions for designing an M809XBH system will yield a design that is easily converted to the M80C196KB.

- Do not base critical timing loops on instruction or peripheral execution times.
- Use equate statements to set all timing parameters, including the baud rate.
- Do not base hardware timings on CLKOUT or XTAL1. The timings of the M80C196KB are different than those of the M8X9XBH, but they will function with standard ROM/EPROM/Peripheral type memory systems.
- Make sure all inputs are tied high or low and not left floating.
- 5. Indexed and indirect operations relative to the stack pointer (SP) work differently on the M80C196KB than on the M8097. On the M8097, the address is calculated based on the un-updated version of the stack pointer. The M80C196KB uses the updated version. The offset for PUSH[SP], POP[SP], PUSH nn[SP] and POP nn[SP] instructions may need to be changed by a count of 2.

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